

# SN54HC534, SN74HC534 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCLS311A – JANUARY 1996 – REVISED MAY 1997

- High-Current 3-State Inverting Outputs Can Drive up to 15 LSTTL Loads
- Package Options Include Plastic Small-Outline (DW) and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

## description

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

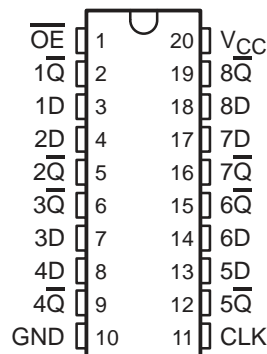
The eight flip-flops of the 'HC534 are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the  $\bar{Q}$  outputs are set to the complement of the logic states that were set up at the data (D) inputs. The 'HC534 are functionally equivalent to the 'HC374, but the 'HC534 have inverted outputs.

An output-enable ( $\overline{OE}$ ) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

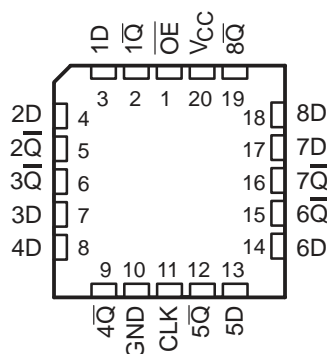
$\overline{OE}$  does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are off.

The SN54HC534 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74HC534 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

SN54HC534 . . . J OR W PACKAGE  
SN74HC534 . . . DW OR N PACKAGE  
(TOP VIEW)



SN54HC534 . . . FK PACKAGE  
(TOP VIEW)



FUNCTION TABLE  
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	$\bar{Q}$
L	$\uparrow$	H	L
L	$\uparrow$	L	H
L	H or L	X	$\bar{Q}_0$
H	X	X	Z



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

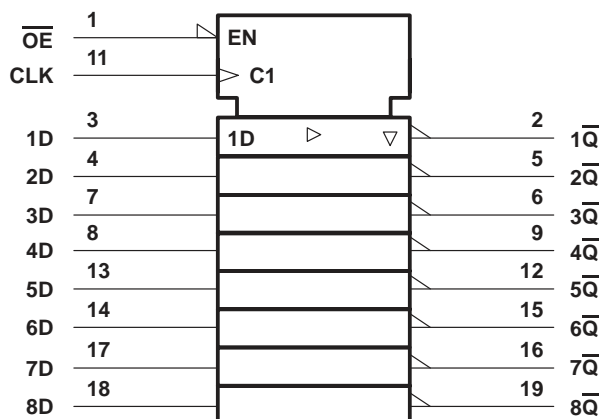
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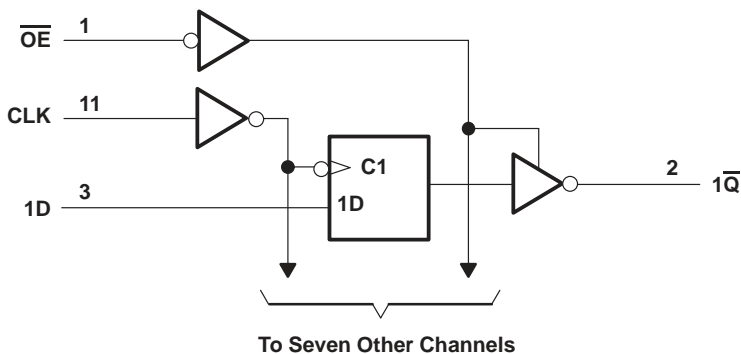
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## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range‡

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 35$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 70$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package .....	97°C/W
N package .....	67°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.



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## recommended operating conditions

		SN54HC534			SN74HC534			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	2	5	6	2	5	6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V		1.5	1.5		V	
		V <sub>CC</sub> = 4.5 V		3.15	3.15			
		V <sub>CC</sub> = 6 V		4.2	4.2			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V		0	0.5	0	0.5	V
		V <sub>CC</sub> = 4.5 V		0	1.35	0	1.35	
		V <sub>CC</sub> = 6 V		0	1.8	0	1.8	
V <sub>I</sub>	Input voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
t <sub>t</sub>	Input transition (rise and fall) time	V <sub>CC</sub> = 2 V		0	1000	0	1000	ns
		V <sub>CC</sub> = 4.5 V		0	500	0	500	
		V <sub>CC</sub> = 6 V		0	400	0	400	
T <sub>A</sub>	Operating free-air temperature	-55		125	-40		85	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC534		SN74HC534		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998		1.9		1.9	V	
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I <sub>OH</sub> = -6 mA	4.5 V	3.98	4.3		3.7		3.84		
		I <sub>OH</sub> = -7.8 mA	6 V	5.48	5.8		5.2		5.34		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		V	
			4.5 V		0.001	0.1		0.1			0.1
			6 V		0.001	0.1		0.1			0.1
		I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26		0.4			0.33
		I <sub>OL</sub> = 7.8 mA	6 V		0.15	0.26		0.4			0.33
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0	6 V		±0.1	±100		±1000		±1000	nA	
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or 0, V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	6 V		±0.01	±0.5		±10		±5	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0	6 V			8		160		80	μA	
C <sub>i</sub>		2 V to 6 V		3	10		10		10	pF	

**SN54HC534, SN74HC534**  
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**WITH 3-STATE OUTPUTS**

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

	$V_{CC}$	$T_A = 25^\circ\text{C}$		SN54HC534		SN74HC534		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$f_{\text{clock}}$ Clock frequency	2 V	0	6	0	4.2	0	5	MHz
	4.5 V	0	31	0	21	0	25	
	6 V	0	36	0	25	0	29	
$t_w$ Pulse duration, CLK high or low	2 V	80		120		100		ns
	4.5 V	16		24		20		
	6 V	14		20		17		
$t_{\text{su}}$ Setup time, data before CLK $\uparrow$	2 V	100		150		125		ns
	4.5 V	20		30		25		
	6 V	17		26		21		
$t_h$ Hold time, data after CLK $\uparrow$	2 V	5		5		5		ns
	4.5 V	5		5		5		
	6 V	5		5		5		

switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC534		SN74HC534		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\text{max}}$			2 V	6	11		4.2		5	MHz	
			4.5 V	31	36		21		25		
			6 V	36	40		25		29		
$t_{\text{pd}}$	CLK	Any $\bar{Q}$	2 V		88	180		270		225	ns
			4.5 V		28	36		54		45	
			6 V		24	31		46		38	
$t_{\text{en}}$	$\overline{\text{OE}}$	Any $\bar{Q}$	2 V		77	150		225		190	ns
			4.5 V		26	30		45		38	
			6 V		23	26		38		32	
$t_{\text{dis}}$	$\overline{\text{OE}}$	Any $\bar{Q}$	2 V		51	150		225		190	ns
			4.5 V		25	30		45		38	
			6 V		23	26		38		32	
$t_t$		Any $\bar{Q}$	2 V		28	60		90		75	ns
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	



**SN54HC534, SN74HC534**  
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switching characteristics over recommended operating free-air temperature range,  $C_L = 150$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC534		SN74HC534		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	CLK	Any $\bar{Q}$	2 V	105	230	345	290	ns			
			4.5 V	35	46	69	58				
			6 V	31	39	58	49				
$t_{en}$	$\overline{OE}$	Any $\bar{Q}$	2 V	95	200	300	250	ns			
			4.5 V	32	40	60	50				
			6 V	29	34	51	43				
$t_t$		Any $\bar{Q}$	2 V	60	210	315	265	ns			
			4.5 V	17	42	63	53				
			6 V	14	36	53	45				

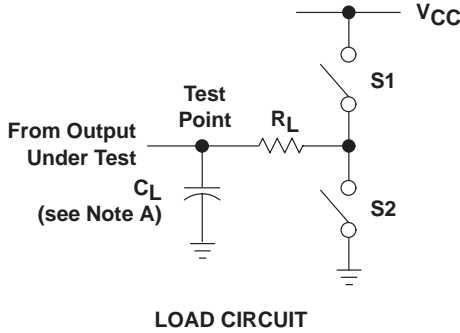
operating characteristics,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance per flip-flop	No load	100	pF

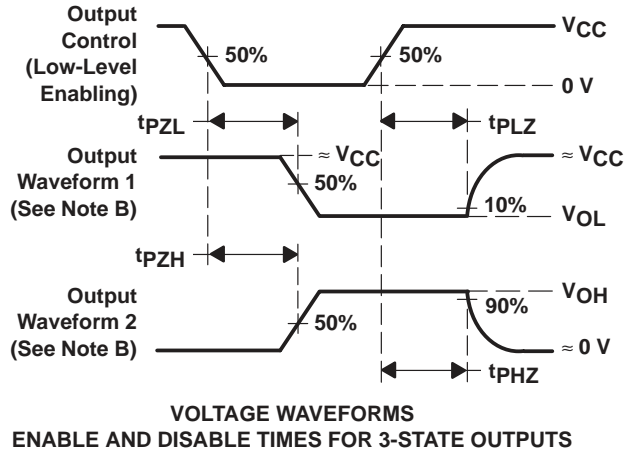
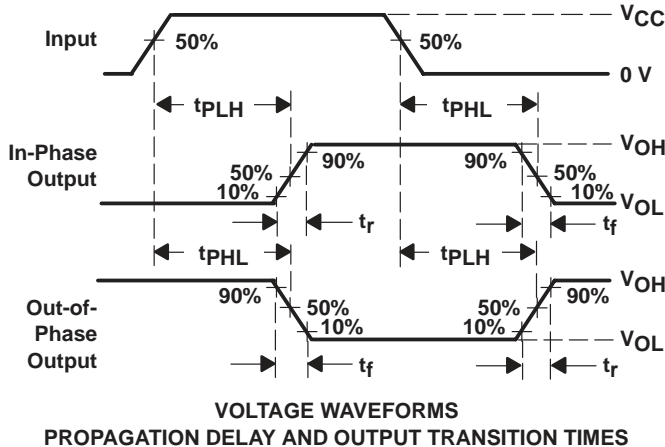
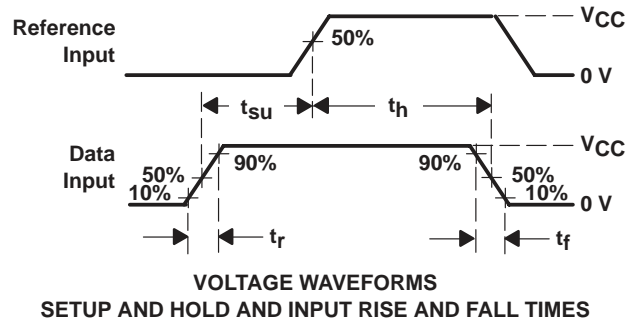
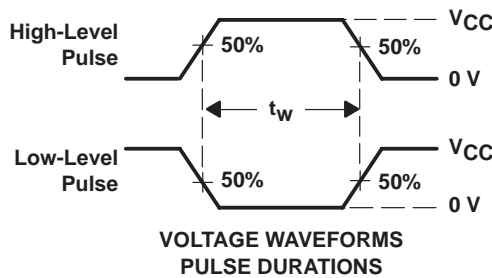
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## PARAMETER MEASUREMENT INFORMATION



PARAMETER	$R_L$	$C_L$	S1	S2
$t_{en}$	1 k $\Omega$	50 pF or 150 pF	Open	Closed
			Closed	Open
$t_{dis}$	1 k $\Omega$	50 pF	Open	Closed
			Closed	Open
$t_{pd}$ or $t_t$	—	50 pF or 150 pF	Open	Open



- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.  
 D. For clock inputs,  $f_{max}$  is measured when the input duty cycle is 50%.  
 E. The outputs are measured one at a time with one input transition per measurement.  
 F.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 H.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74HC534DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		
SN74HC534DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85		
SN74HC534N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

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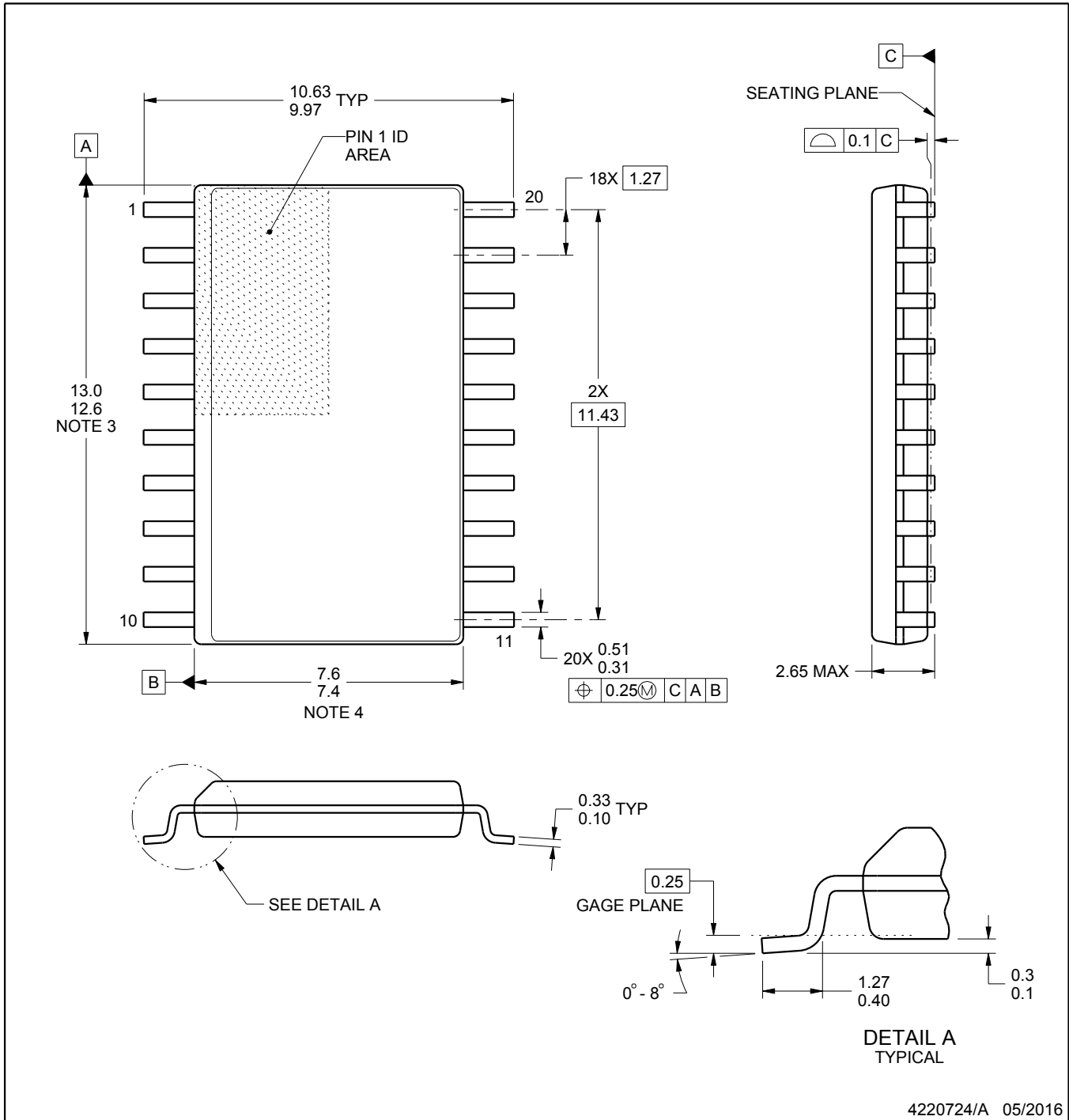
# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

**NOTES:**

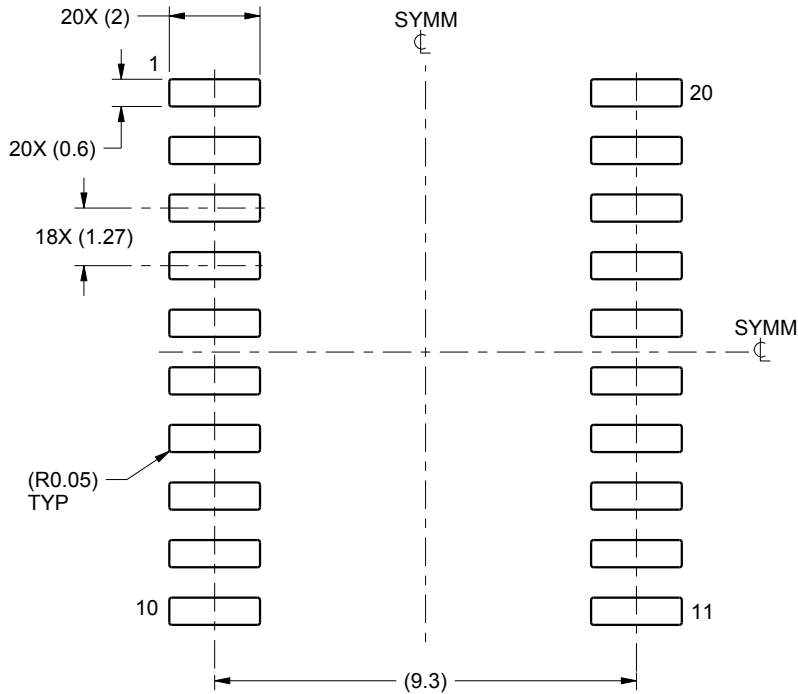
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

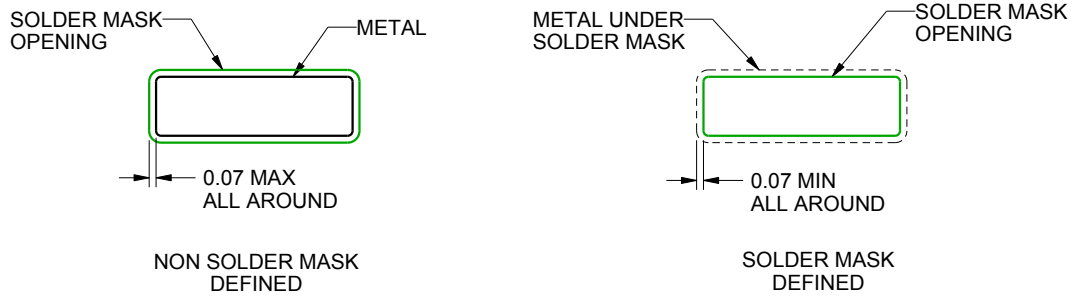
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

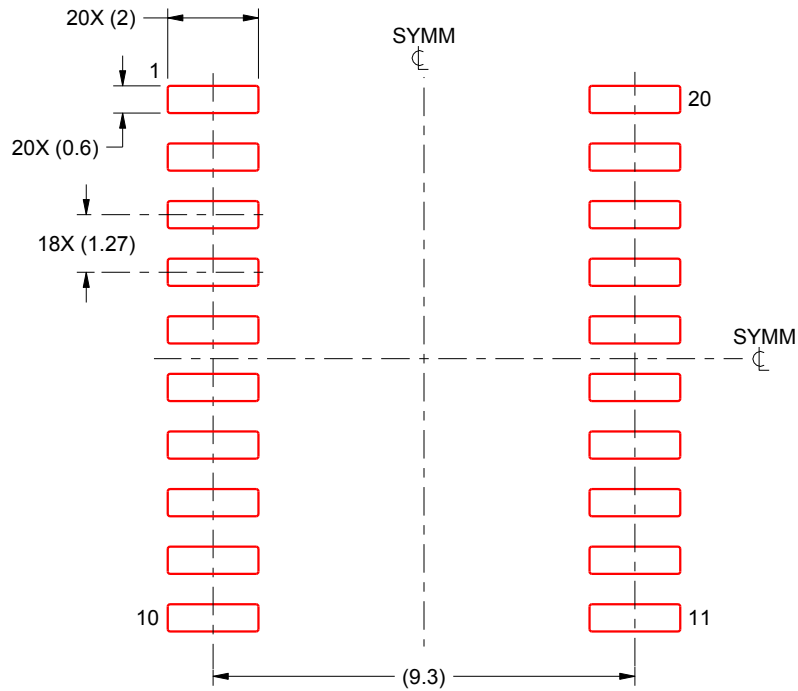
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
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